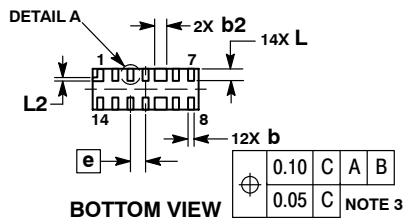
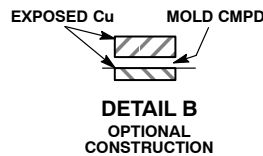
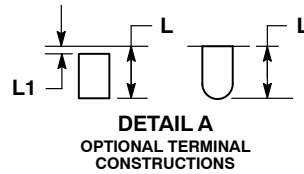
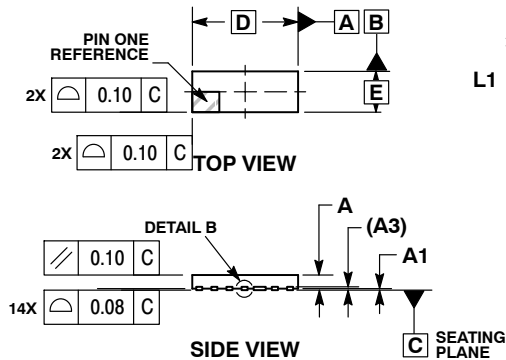




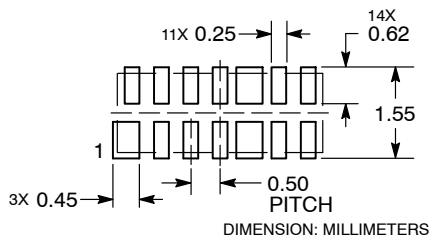
**SCALE 2:1**

UDFN14, 3.5x1.35, 0.5P  
CASE 517CQ  
ISSUE O

DATE 17 JAN 2013



### RECOMMENDED SOLDERING FOOTPRINT\*



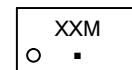
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
b2	0.35	0.45
D	3.50 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.30	0.50
L1	0.00	0.15
L2	0.20 REF	

### GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

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<b>DESCRIPTION:</b>	<b>UDFN14, 3.5X1.35, 0.5P</b>	<b>PAGE 1 OF 1</b>

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